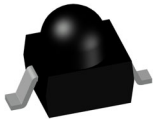


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

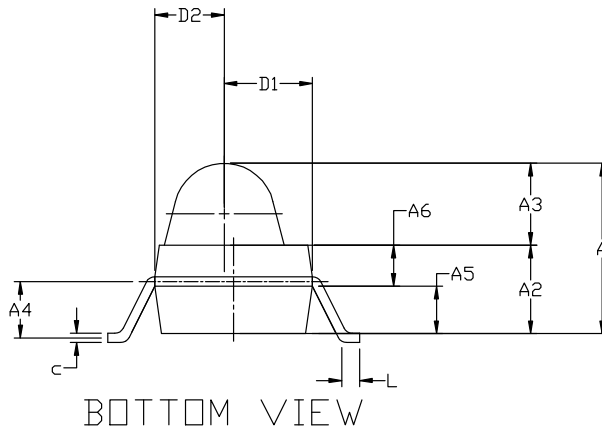
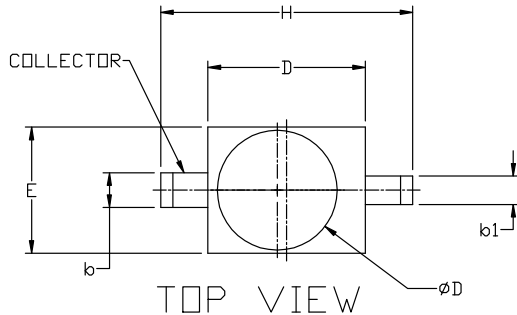


T-3/4 2.50x2.00
CASE 100EH
ISSUE O

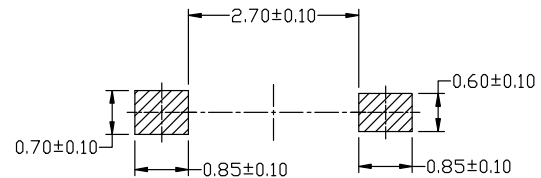
DATE 14 SEP 2023

NOTES:

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
3. 2MM GULLWING DETECTOR.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.500	2.700	2.900
A2	1.300	1.400	1.500
A3	1.200	1.300	1.400
A4	0.750	0.850	0.950
A5	0.650	0.750	0.850
A6	0.550	0.650	0.750
b	0.450	0.550	0.650
b1	0.350	0.450	0.550
c	0.100	0.150	0.200
D	2.300	2.500	2.700
D1	1.200	1.400	1.600
D2	0.900	1.100	1.300
E	1.800	2.000	2.200
H	3.800	4.000	4.200
L	0.200	0.300	0.400
ϕD	1.700	1.900	2.100
R1	0.700	0.800	0.900



RECOMMENDED MOUNTING FOOTPRINT*
 *FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

DOCUMENT NUMBER:	98AON57119H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	T-3/4 2.50x2.00	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.